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SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

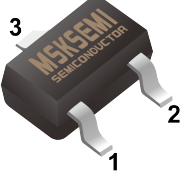
BC817-16W/25W/40W

Product specification

FEATURES

- For General AF Applications
- High Collector Current
- High Current Gain

Reference News

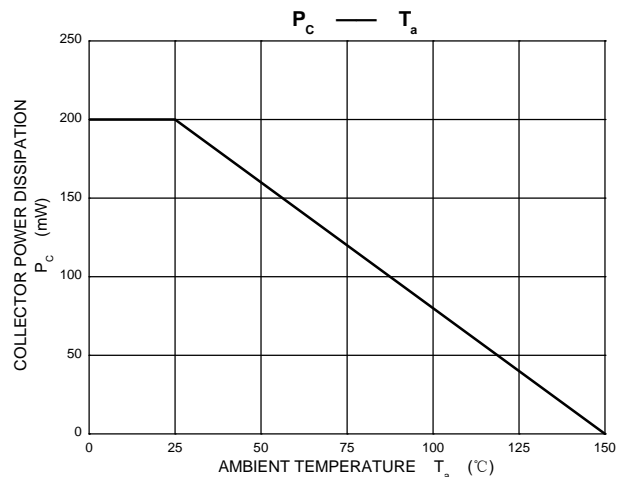
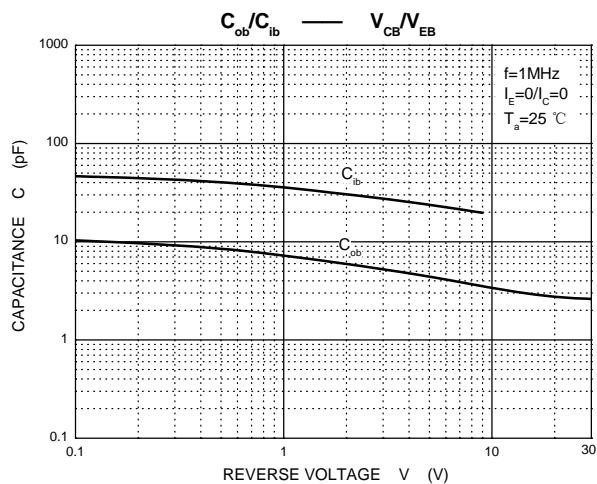
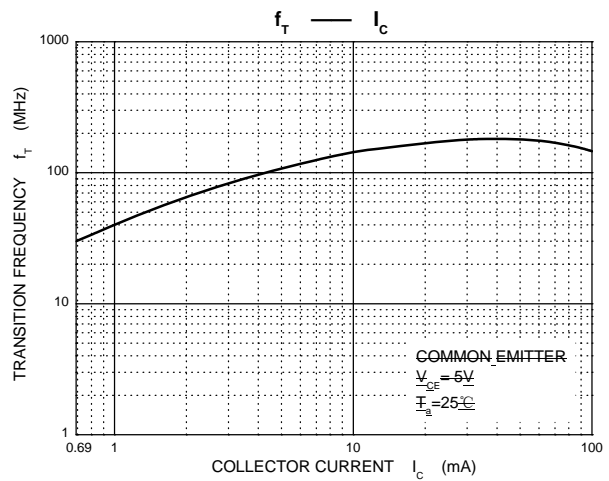
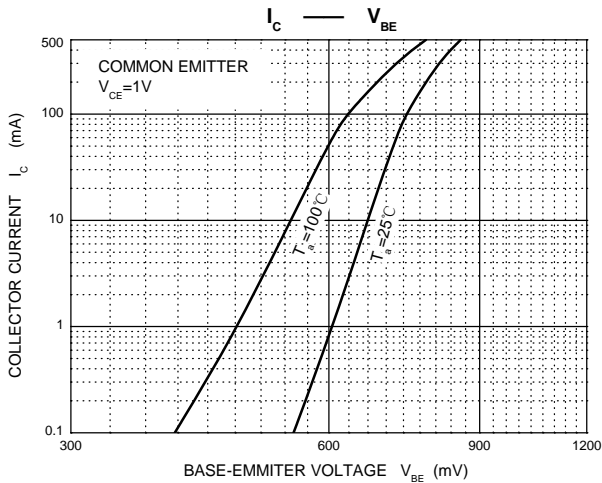
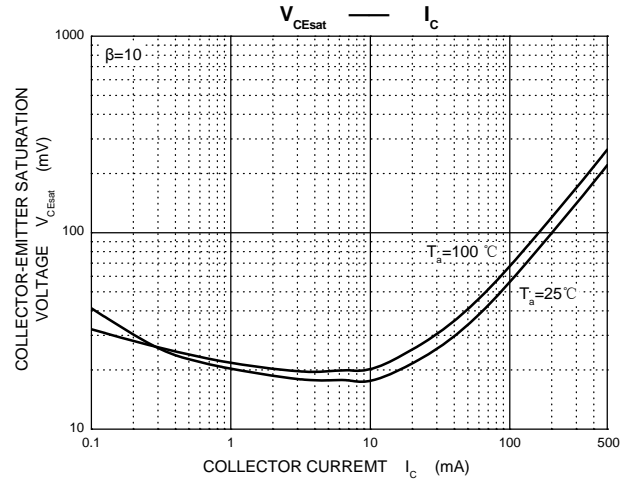
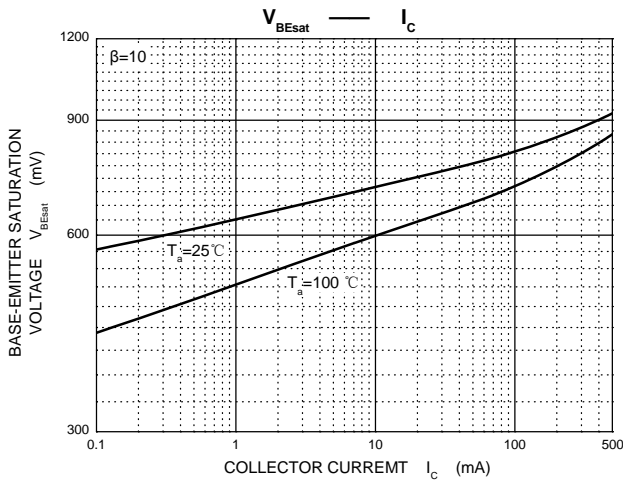
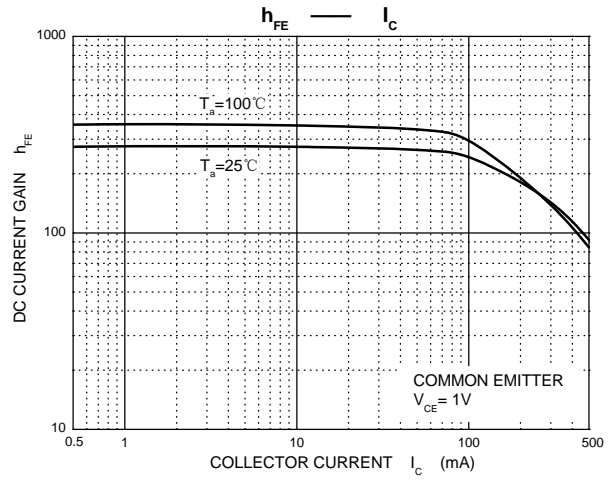
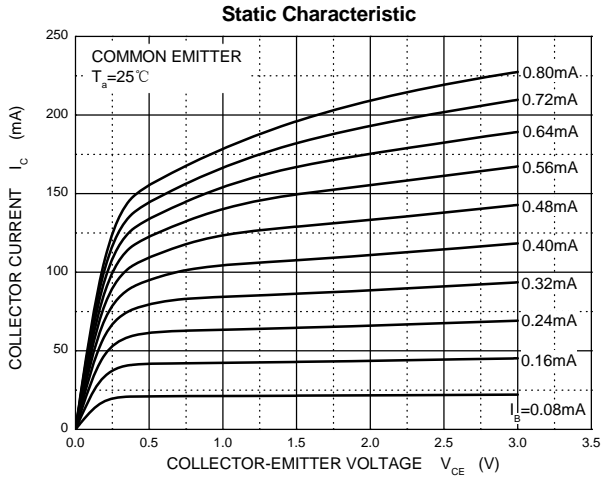
PACKAGE OUTLINE	Rank	BC817-16W	BC817-25W	BC817-40W
 <div style="border: 1px solid black; padding: 5px; margin-left: 10px;"> 1.BASE 2.EMITTER 3.COLLECTOR </div>	Range	100-250	160-400	250-600
	MARKING	6A	6B	6C
SOT-323				

MAXIMUM RATINGS (Ta=25°C unless otherwise noted)

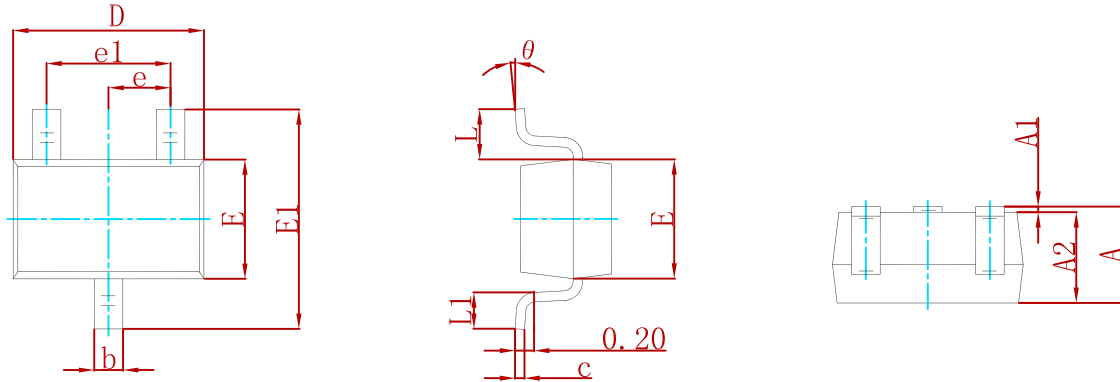
Symbol	Parameter	Value	Unit
V _{CB0}	Collector-Base Voltage	50	V
V _{CEO}	Collector-Emitter Voltage	45	V
V _{EBO}	Emitter-Base Voltage	5	V
I _c	Collector Current -Continuous	0.5	A
P _C	Collector Dissipation	0.2	W
R _{θJA}	Thermal Resistance from Junction to Ambient	625	°C/W
T _J , T _{stg}	Operation Junction and Storage Temperature Range	-55~+150	°C

ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Collector-base breakdown voltage	V _{(BR)CBO}	I _C =10μA, I _E =0	50			V
Collector-emitter breakdown voltage	V _{(BR)CEO}	I _C =10mA, I _B =0	45			V
Emitter-base breakdown voltage	V _{(BR)EBO}	I _E =1μA, I _C =0	5			V
Collector cut-off current	I _{CBO}	V _{CB} =20V, I _E =0			0.1	μA
Emitter cut-off current	I _{EBO}	V _{EB} =5V, I _C =0			0.1	μA
DC current gain	h _{FE(1)}	V _{CE} =1V, I _C =100mA	100		600	
	h _{FE(2)}	V _{CE} =1V, I _C =500mA	40			
Collector-emitter saturation voltage	V _{CE(sat)}	I _C =500mA, I _B =50mA			0.7	V
Base-emitter saturation voltage	V _{BE(sat)}	I _C =500mA, I _B =50mA			1.2	V
Base-emitter voltage	V _{BE(ON)}	V _{CE} =1V, I _C =500mA			1.2	V
Transition frequency	f _T	V _{CE} =5V, I _C =10mA, f=100MHz	100			MHz
Collector output capacitance	C _{ob}	V _{CB} =10V, f=1MHz			5	pF

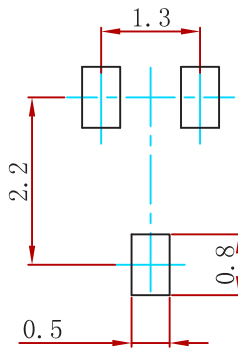


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:
 1. Controlling dimension: in millimeters.
 2. General tolerance: ± 0.05 mm.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
BC817-16W/25W/40W	SOT-323	3000

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